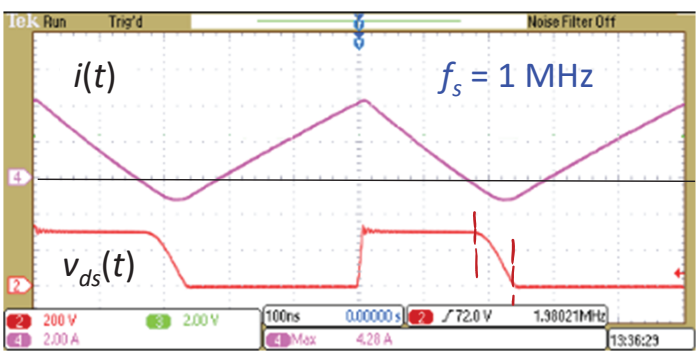
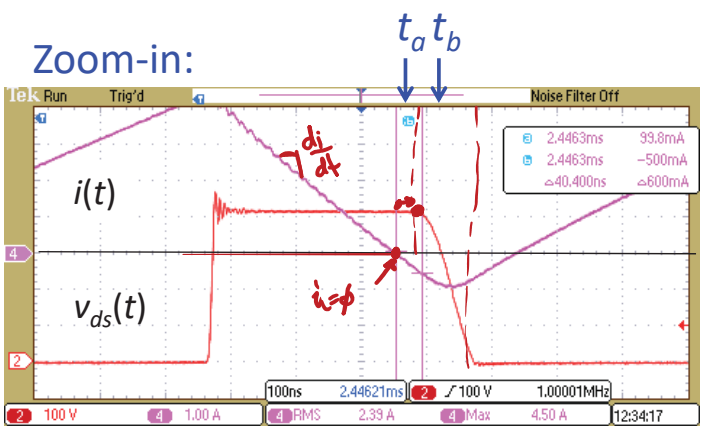
150-to-400V, 150W Boost

EXPERIMENTAL EXAMPLE

ZVS with Si diode



Zoom-in:

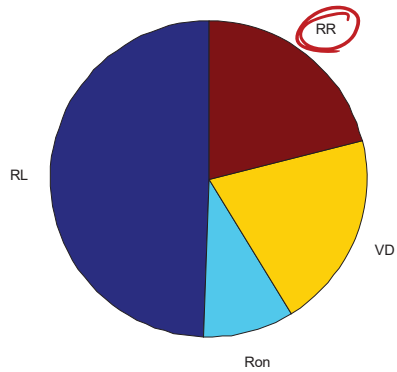


- ZVS turn-ON
  - Eliminated losses due to C_{sw} discharge during turn-ON transient
  - Eliminated losses due to MOSFET di_F/dt during turn-ON transient
- Diode reverse recovery still impacts the waveforms and losses
- Increased current ripple
  - Increased conduction losses (by >30%)
  - Increased dv_{ds}/dt upon turn-OFF, MOSFET turn-OFF speed is more important

D. Costinett, D. Maksimovic, R. Zane, A. Rodríguez and A. Vázquez, "Comparison of reverse recovery behavior of silicon and wide bandgap diodes in high frequency power converters"

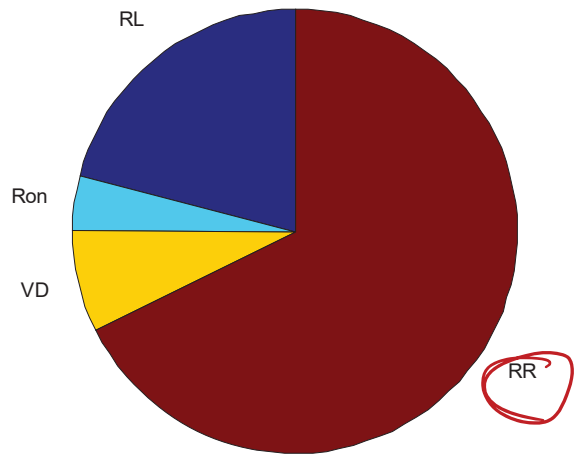
Loss Breakdown: Soft-Switched Si Boost

f_s = 100 kHz
P_{loss} = 5.7 W, η = 98.1%



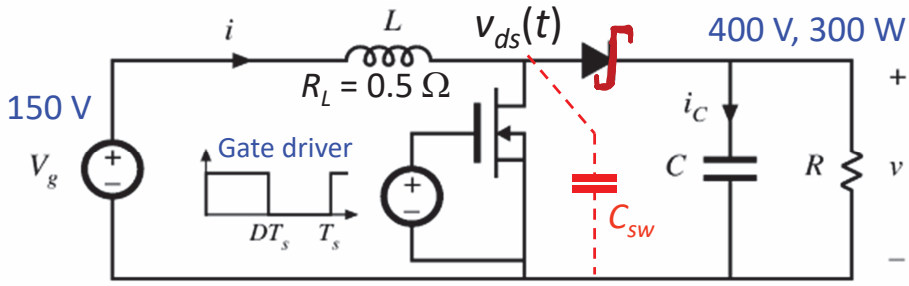
Reverse-recovery:
21% of the total loss

f_s = 1 MHz
P_{loss} = 17.7 W, η = 94.4 %
Experiment: η = 95.1 %

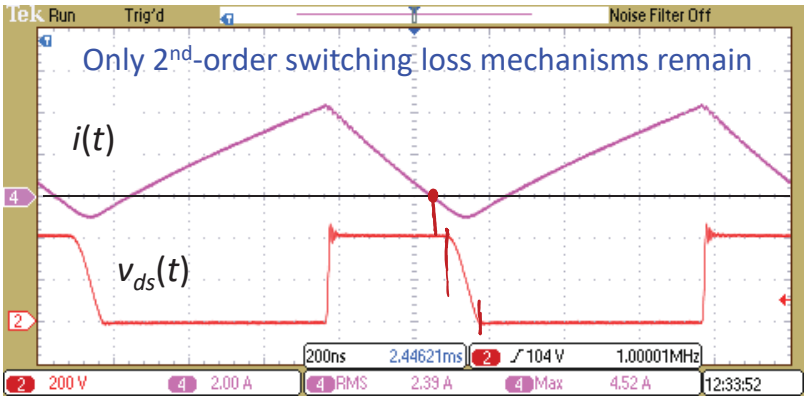


Reverse-recovery:
68% of the total loss

Soft-switched SiC diode



SiC diode, "soft-switched" operation



f_s = 1 MHz

MOSFET

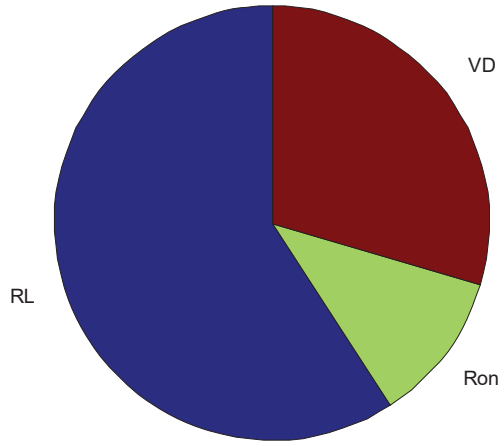
- di_F/dt = 200 A/μs
- $C_{ds,eq}$ = 45 pF
- R_{on} = 0.15 Ω

SiC diode

- t_{rr} = 0, Q_{rr} = 0
- $2C_{d,Qeq}$-$C_{d,eq}$ = 64 pF
- V_D = 1.8 V

Soft-switched Boost with SiC diode

Conduction losses only, 2nd-order switching losses not included in the model



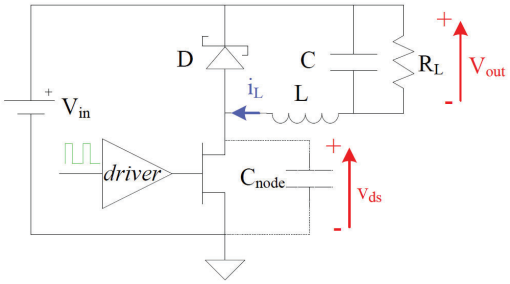
100 kHz or 1 MHz
98.5% efficiency
P_{loss} = 4.5 W

Experiments:
98.7% at 1 MHz
98.0% at 2 MHz

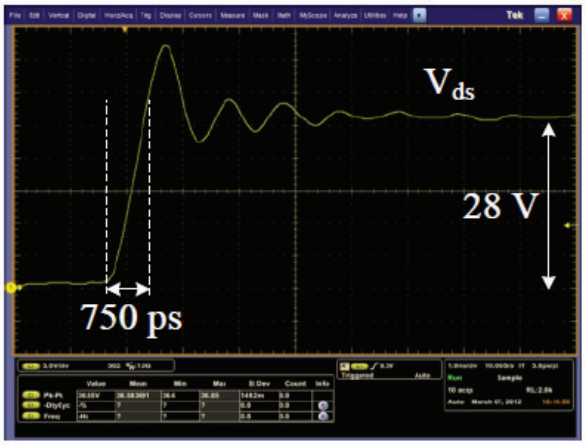
Power supply technology limits become dominated by:

- Magnetics
- 2nd-order switching loss mechanisms, e.g. gate-drive losses, parasitic inductances (layout and packaging)
- Gate-drive circuitry and controllers to support high-frequency operation

Speed Limitations WBG Devices



Standard hard-switched PWM operation at 50 MHz
dv_{ds}/dt dominated by probe (4 pF) capacitance



TriQuint TGF2023-02
12W, DC-to-18 GHz
RF/microwave HEMT

FOM for switching applications
$C_{ds}R_{on} \approx 1\ \Omega$pF
$Q_gR_{on} \approx 10\ \Omega$pC

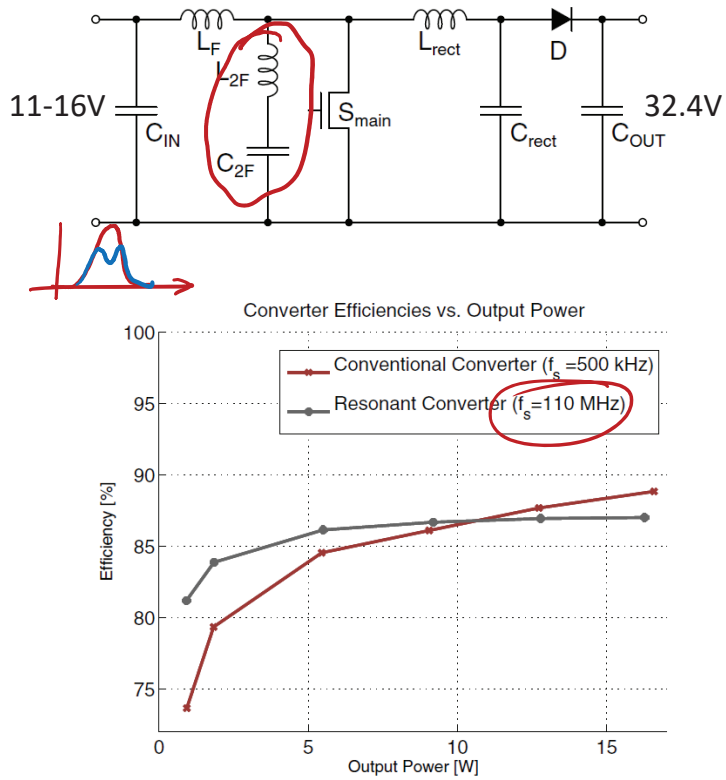
Emerging GaN HEMT devices may enable completely new RF-based design approaches in power electronics

M. Rodríguez, G. Stahl, D. Costinett and D. Maksimović, "Simulation and characterization of GaN HEMT in high-frequency switched-mode power converters,"

VHF power electronics [11]

Resonant Design		
Component	**Value**	**Type**
L_F	33 nH	Coilcraft 1812SMS
L_{2F}	12.5 nH	Coilcraft A04TG
L_{rect}	22 nH	1812SMS
C_{2F}	39 pF	ATC100A
C_{rect}	10 pF	ATC100A
C_{out}	75 μF	Multilayer Ceramics
C_{in}	22 μF	Multilayer Ceramics
S_{main}		Freescale MRF6S9060
D		Fairchild S310

Conventional Design		
Component	**Value**	**Type**
L_{boost}	10 μH	Coilcraft D03316T-103ML
C_{out}	75 μF	Multilayer Ceramics
C_{in}	22 μF	Multilayer Ceramics
S_{main}		LT1371HV
D		Fairchild S310



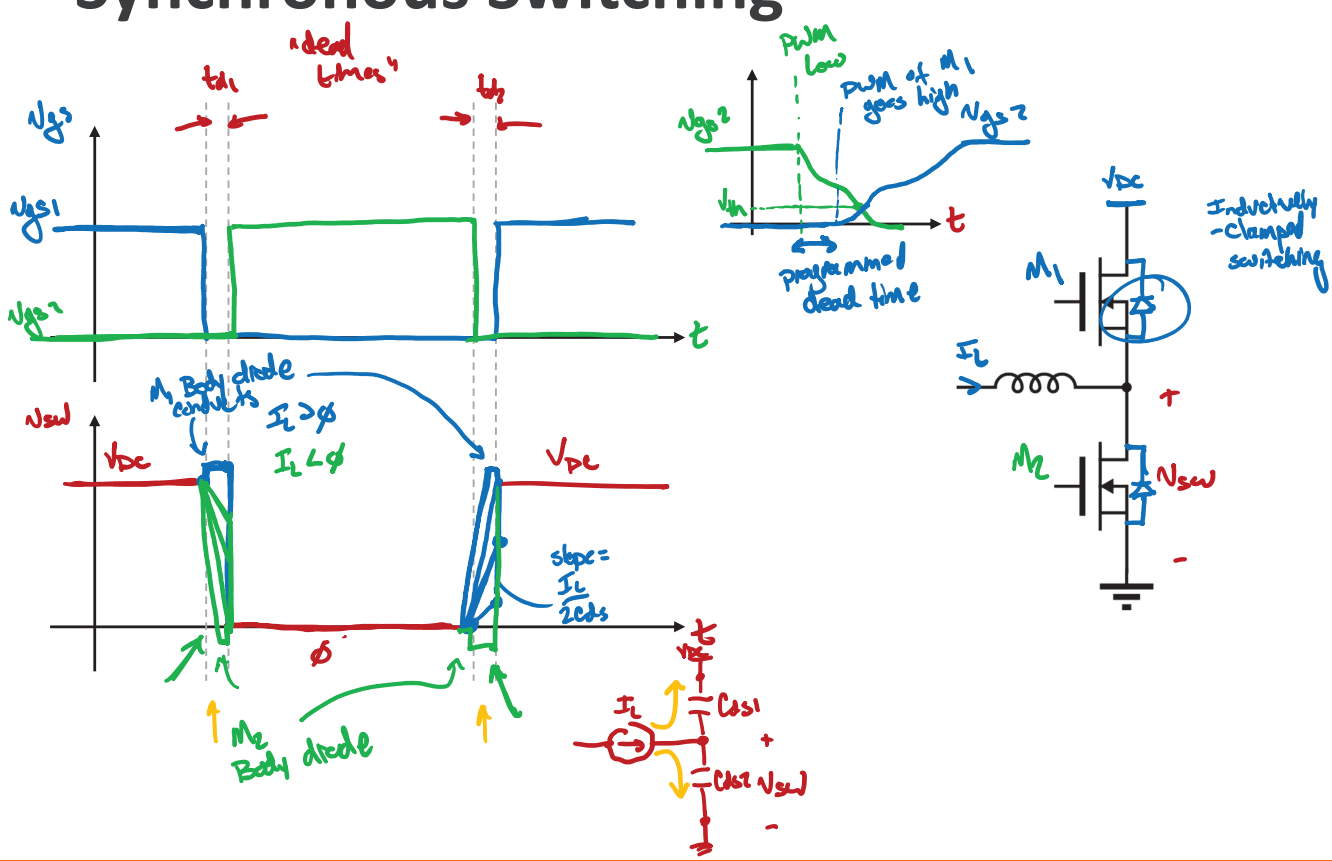
[11] D.J. Perreault, et..al. "Opportunities and challenges in very high frequency power conversion," IEEE APEC 2009.

Topics Covered

- **Course Topics**
  - High Frequency Power Conversion
    - Switching losses and device selection
    - Resonance in power electronics
    - Soft switching (ZVS and ZCS)
    - Magnetics design
  - Non-resonant soft switching converters
    - Constant frequency control
    - State-plane analysis
    - Resonant switches
    - Modeling and Simulation
    - Discrete time models
  - Resonant Converters
    - Resonant converter topologies
    - Sinusoidal analysis
    - AC-modeling and frequency modulation
    - State-plane analysis
  - Applications and practical issues of high frequency converters

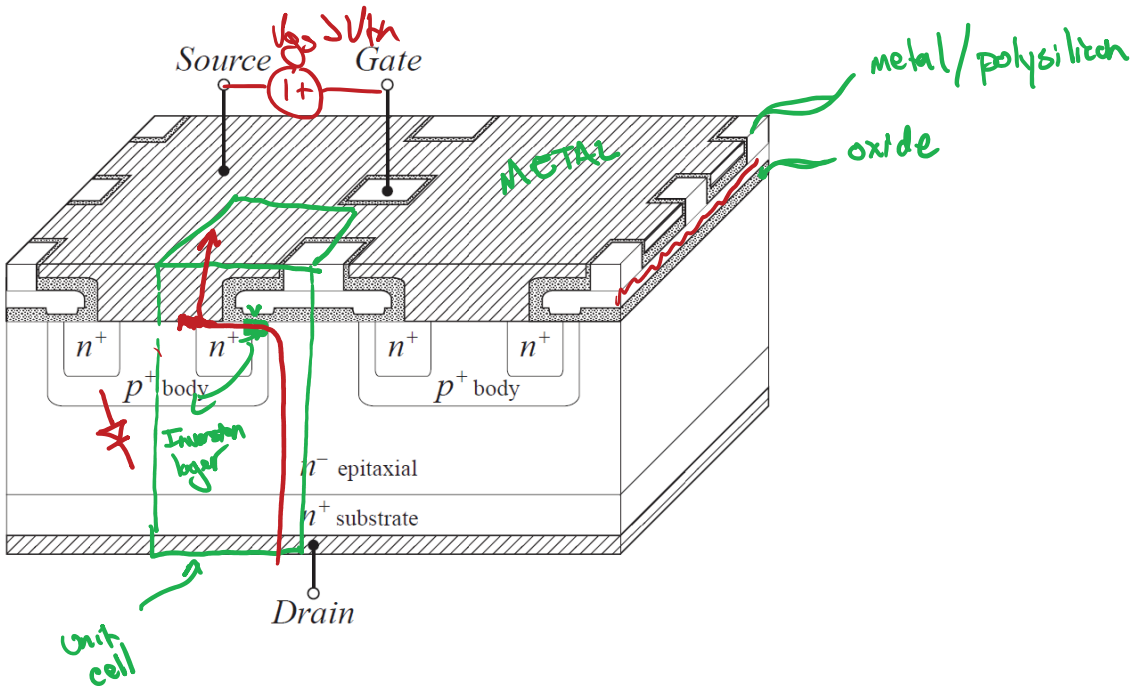
HARD SWITCHING ANALYSIS

Synchronous Switching

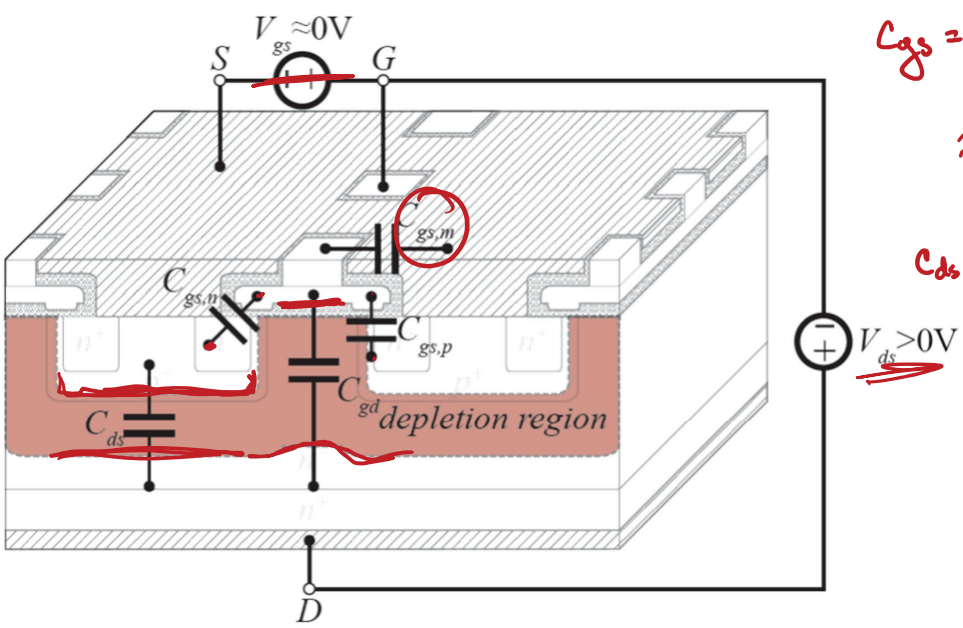


MOSFET Cross Section

VDMOS



MOSFET Depletion Capacitance



$C_{gs} = C_{gs,m} + C_{gs,n} + C_{gs,p}$

$\approx$ constant as V_{ds} changes

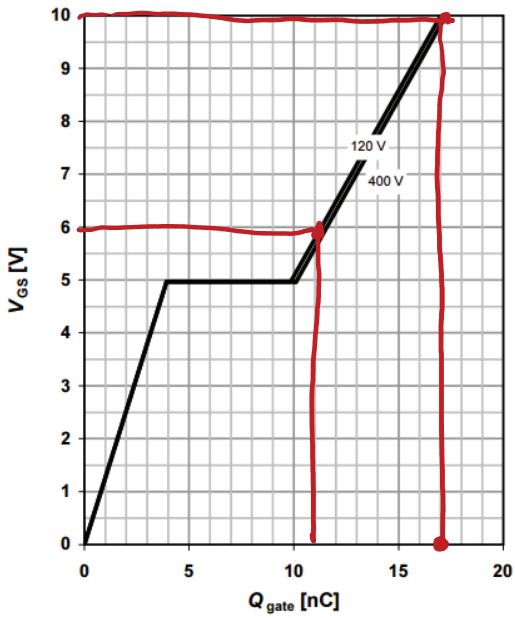
C_{ds} & $C_{gd} = f(V_{ds})$

Gate Charge

9 Typ. gate charge

V_{GS}=f(Q_{gate}); I_D=5.2 A pulsed

parameter: V_{DD}



Power supply voltage of gate driver

$$P_g = V_{DR} Q_g f_s$$